

SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

Reverse Voltage - 50 to 1000 V

Forward Current - 1 A

FEATURES

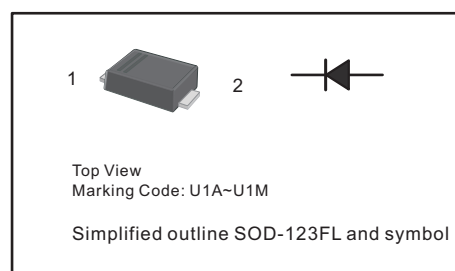
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 15mg/0.00053oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US1AW	US1BW	US1DW	US1GW	US1JW	US1KW	US1MW	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ °C}$	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.0		1.3		1.65		V	
Maximum DC Reverse Current $T_a = 25\text{ °C}$ at Rated DC Blocking Voltage $T_a = 125\text{ °C}$	I_R	5 100							μA
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50				75			ns
Typical Junction Capacitance ⁽²⁾	C_j	15							pF
Typical Thermal Resistance ⁽³⁾	$R_{\theta JA}$	85							$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^{\circ}\text{C}$

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(3) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

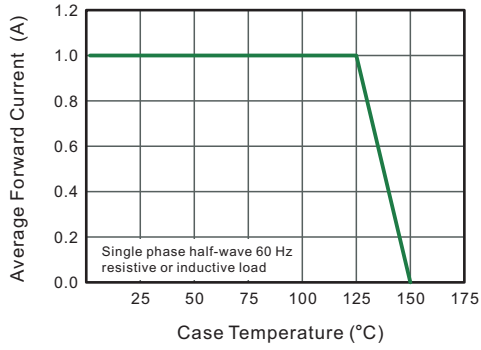


Fig.2 Typical Reverse Characteristics

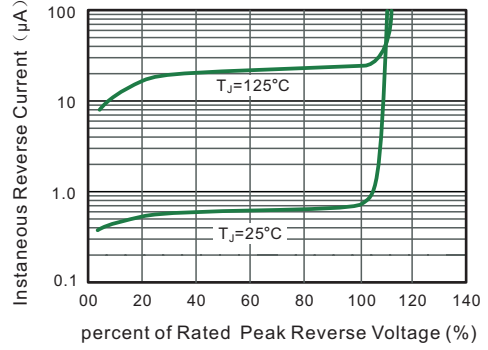


Fig.3 Typical Forward Characteristics

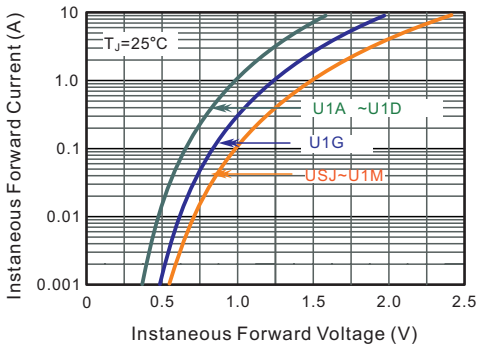


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

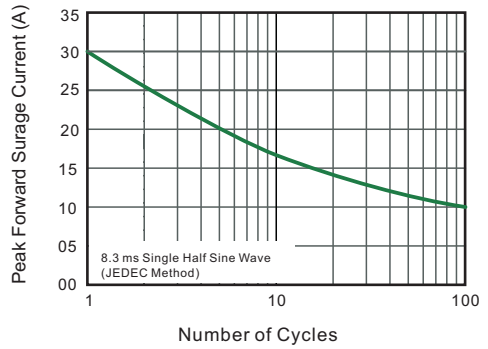


Fig.5- Typical Transient Thermal Impedance

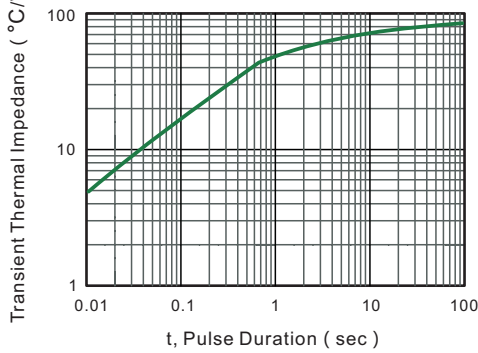
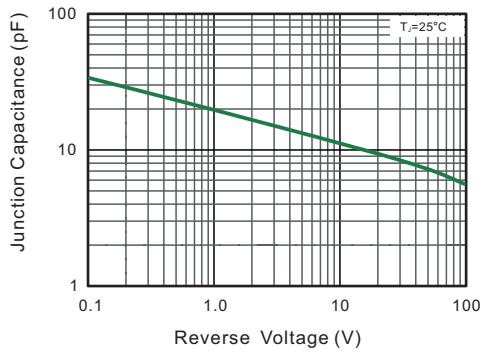


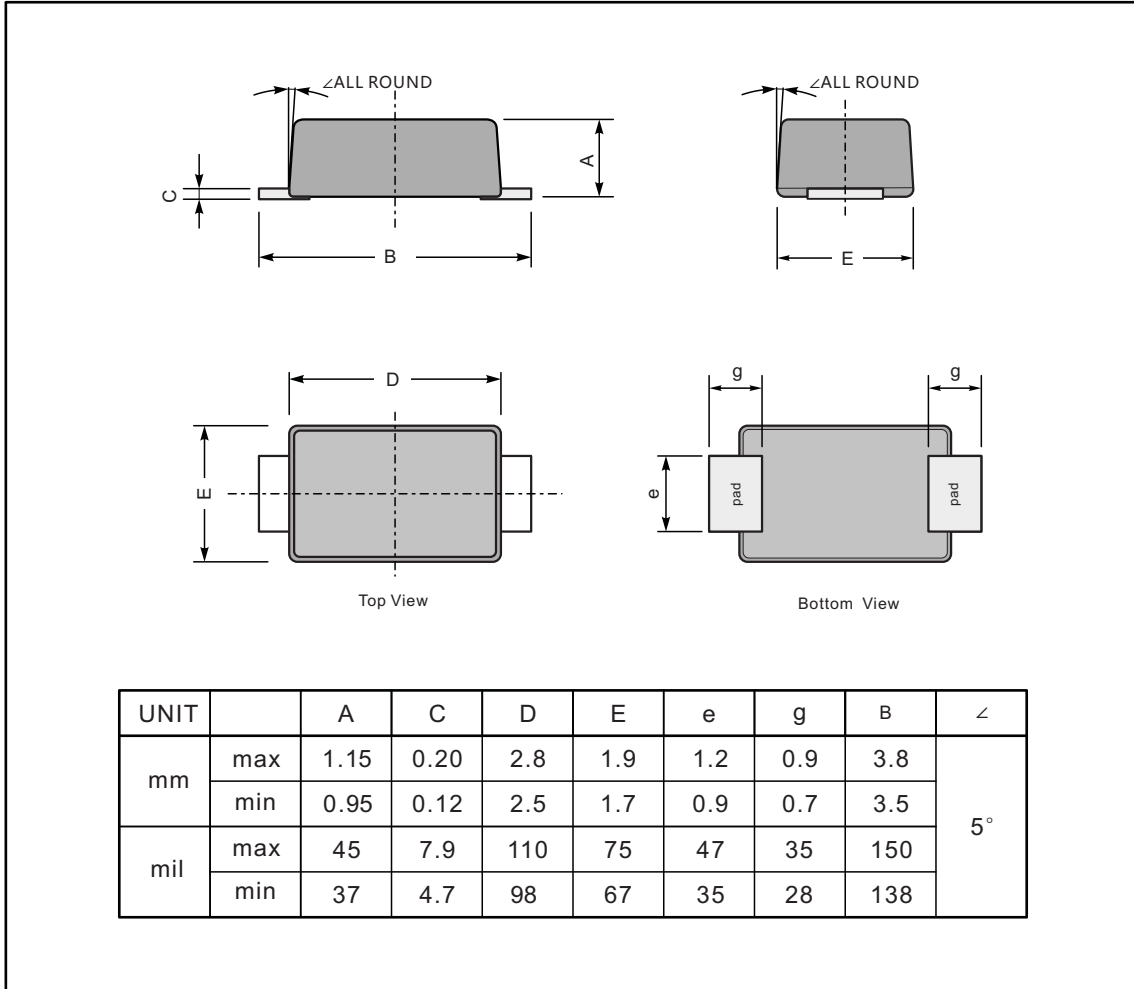
Fig.6 Typical Junction Capacitance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123FL



The recommended mounting pad size

